

METAL EDGE GRINDING WHEEL

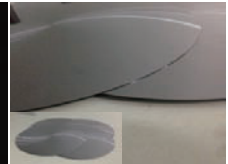
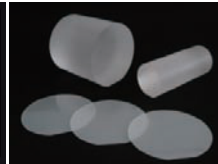
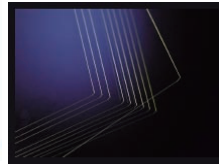


Advantages

- Allowing for high precision and a wide range of groove profiles
- Uniform grinding on top and bottom layer with high edge strength
- Long-lasting groove profile
- Double mesh wheel (rough & Fine grinding) is applicable into one wheel

Application

LCD Panel, Bare glass, Sapphire and Silicon wafer edge grinding

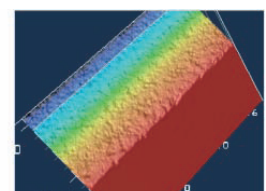
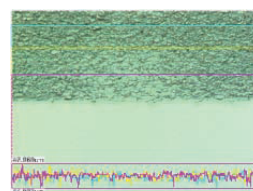
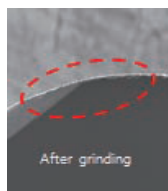


Available Product Spec.

Type	Diameter	Thickness	Grit size	Bond type
MD-DW	φ 8 ~ φ 100	5 ~ 20mm	#325 ~ #3000	Metal
MD-1FF6Y	Φ40 ~ φ 200	5 ~ 80mm		

Performance Data

Applicaton	Edge Strength	Life time	Wheel wear	Chipping size
Panel grinding	120~130 (Mpa)	100 (cell/groove)	35~40 (μm)	< 30μm



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